Title (en)

Phenol-functional organosilicon compounds and method for the preparation thereof

Title (de)

Phenolfunktionelle Organosilikonverbindungen und Verfahren zu deren Herstellung

Title (fr)

Composés organosiliciques à fonction phénolique et procédé pour les préparer

Publication

EP 1041076 A3 20020410 (EN)

Application

EP 00106058 A 20000329

Priority

JP 9057699 A 19990331

Abstract (en)

[origin: EP1041076A2] A phenol-functional organosilicon compound having the formula: <CHEM> wherein A is hydrogen or a residue afforded by the removal of n hydroxyl groups from an m-valent alcohol, each R is independently a monovalent hydrocarbon group free of aliphatic unsaturation, each R<1> is independently a divalent hydrocarbon group containing at least 2 carbon atoms, m and n are natural numbers wherein m ≥ n, p is 0 or 1, and Y is a phenol group having the formula: <CHEM> wherein R<3> is alkyl and q is from 0 to 4. Also, a method of preparing a phenol-functional organosilicon compound.

IPC 1-7

C07F 7/18; C07F 7/08; C08L 83/04

IPC 8 full level

C07B 61/00 (2006.01); **C07F 7/08** (2006.01); **C07F 7/18** (2006.01)

CPC (source: EP KR US)

B01J 23/42 (2013.01 - KR); **C07F 7/0834** (2013.01 - KR); **C07F 7/0836** (2013.01 - EP US); **C07F 7/1804** (2013.01 - EP US)

Citation (search report)

- [A] US 5998509 A 19991207 - HAYASE RUMIKO [JP], et al
- [A] DATABASE CHEMICAL ABSTRACTS [online] 4 November 1985 (1985-11-04), HAYASE, R. ET AL.: "Resin composition for sealing semiconductor devices", XP002186862, retrieved from CHEMICAL ABSTRACTS Database accession no. 103:152126 & JP S6070729 A 19850422 - SHINETSU CHEM IND CO

Cited by

CN110776640A; WO2017189077A1

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)

EP 1041076 A2 20001004; **EP 1041076 A3 20020410**; **EP 1041076 B1 20041013**; DE 60014737 D1 20041118; DE 60014737 T2 20060202; JP 2000281686 A 20001010; JP 4408982 B2 20100203; KR 100665486 B1 20070110; KR 20000063048 A 20001025; TW I277618 B 20070401; US 6172252 B1 20010109

DOCDB simple family (application)

EP 00106058 A 20000329; DE 60014737 T 20000329; JP 9057699 A 19990331; KR 20000016102 A 20000329; TW 89106090 A 20000331; US 53193500 A 20000321